ON Semiconductor®



ARRAYX-BOB3-16S-GEVK: C-Array 3mm 4x4 Sum BOB

The ArrayX-BOB3-16S is an evaluation board allowing easy access to the sum of all of standard pixel signals of a SensL ArrayC-30035-16P, 3mm 4x4 SiPM array, in addition to all of the individual fast output signals. The Summed Breakout Board has a centrally located Hirose 40-way connector DF17(2.0)-40DS-0.5V(57). This connector mates with the Hirose DF17(2.0)-40DP-0.5V(57) board-to-board connector on the ArrayC-30035-16P. See Figure 7 in the previous section for information on orientating the array on the BOB. A schematic of the board is shown in Figure 8 below.

Fast signals: All of the fast output signals (Fn) from the array are routed via the mating connectors to header pins. These pins are formed by two 20-way (10x2 row) 2.54mm pitch headers; J2 and J3. Each of the headers also has 2 pins that connect to the common cathode (CM) and 2 pins left unconnected (NC) to allow prototyping for evaluation purposes.



Two SMA connectors and Balun transformers are provided with 4-pin headers to allow any fast signal to be connected directly to the SMA or via the transformer using jumper wires.

Evaluation/Development Tool Information

Product	Status	Compliance	Short Description	Parts Used	Action
ARRAYX-BOB3-16S-GEVK	Active		C-Array 3mm 4x4 Sum BOB	ARRAYC-30035-16P-PCB	Contact Local Sales Office